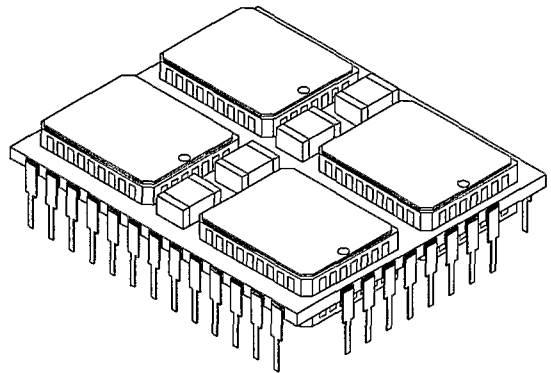


DESCRIPTION:

The DPS256Q8 is a 2 Megabit (256K X 8) CMOS Static RAM module constructed on a co-fired ceramic substrate using eight low power 32K X 8 CMOS Static RAMs in leadless chip carrier packages.

The DPS256Q8 is offered in a 42-pin Cer-Quad Package which allows two megabits of memory to be placed in less than 1.6 square inches of board space.

The DPS256Q8 is available in fast access time over the commercial, industrial and military temperature ranges, with minimal power consumption.

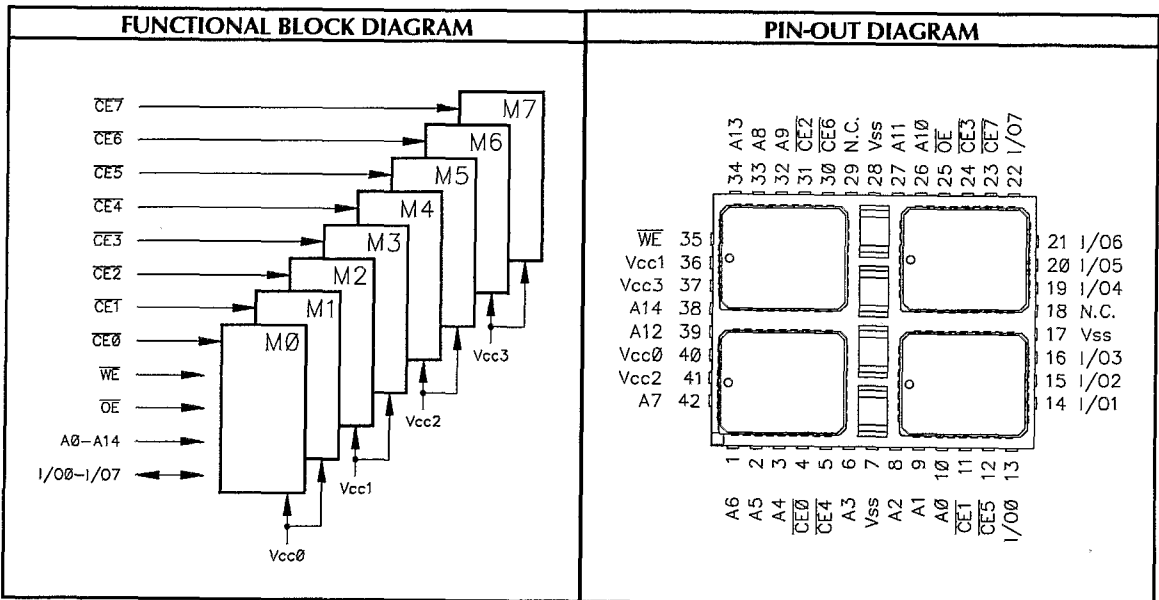


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FEATURES:

- High-Density 2 Megabit (256K X 8) CMOS Static RAM Module
- Access Times: 25, 35, 45, 55, 70, 85, 100, 120, 150ns (max.)
- Inputs/Outputs Directly TTL Compatible
- Single +5V (±10% Tolerance) Power Supply
- Low Power CMOS Design
- Low Data Retention Voltage: 2.0V min.
- Modules available with semiconductor components compliant to MIL-STD-883, Class B, Rev. C.
- 42-Pin, Cer-Quad Package for Maximum Space Savings
- Module Weight is 16 Grams

PIN NAMES	
A0-A14	Address Inputs
I/O0-I/O7	Data In/Out
$\overline{CE}0 - \overline{CE}7$	Chip Enable
\overline{WE}	Write Enable
\overline{OE}	Output Enable
Vcc0 - Vcc3	Power (+5V) Bank
Vss	Ground
N.C.	No Connect



CAPACITANCE ⁴ : T _A = 25°C, F = 1.0MHz				
Symbol	Parameter	Max.	Unit	Condition
C _{CE}	Chip Enable	35	pF	V _{IN} = 0V
C _{ADR}	Address Input	80		
C _{WE}	Write Enable	80		
C _{OE}	Output Enable	80		
C _{I/O}	Data Input/Output	80		

ABSOLUTE MAXIMUM RATINGS ³			
Symbol	Parameter	Value	Unit
T _{STC}	Storage Temperature	-65 to +150	°C
T _{BIAS}	Temperature Under Bias	-55 to +125	°C
V _{CC}	Supply Voltage ¹	-0.5 to +7.0	V
V _{I/O}	Input/Output Voltage ¹	-0.5 to V _{CC} + 0.5	V

RECOMMENDED OPERATING RANGE ¹					
Symbol	Characteristic	Min.	Typ.	Max.	Unit
V _{CC}	Supply Voltage	4.5	5.0	5.5	V
V _{IH}	Input HIGH Voltage	2.2		V _{CC} +0.3	V
V _{IL}	Input LOW Voltage	-0.5 ²		0.8	V

TRUTH TABLE					
Mode	\overline{CE}	\overline{OE}	\overline{WE}	I/O Pin	Supply Current
Not Selected	H	X	X	HIGH-Z	Standby
DOUT Disable	L	H	H	HIGH-Z	Active
Read	L	L	H	DOUT	Active
Write	L	X	L	DIN	Active

L = LOW H = HIGH X = Don't Care

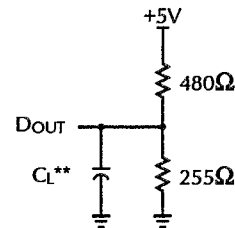
AC TEST CONDITIONS	
Input Pulse Levels	0V to 3.0V
Input Pulse Rise and Fall Times	5ns*
Input Timing Reference Levels	1.5V

* Transition between 0.8V and 2.2V.

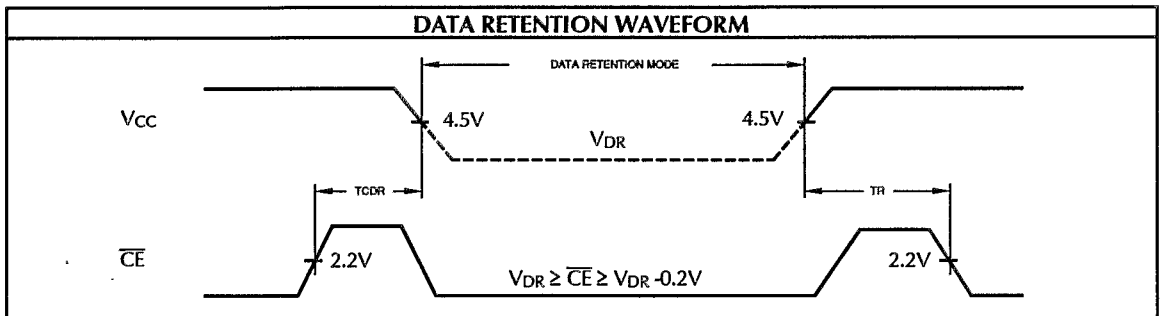
AC TEST CONDITIONS		
Load	C _L	Parameters Measured
1	100pF	except t _{CLZ} , t _{CHZ} , t _{WHZ} , t _{WLZ} , t _{OLZ} and t _{OHZ}
2	5 pF	t _{CLZ} , t _{CHZ} , t _{WHZ} , t _{WLZ} , t _{OLZ} and t _{OHZ}

Figure 1. Output Load

** Including Probe and Jig Capacitance.



DATA RETENTION CHARACTERISTICS						
Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
V _{DR}	Data Retention Voltage	$\overline{CE} \geq V_{CC} - 0.2V$	2.0	5.0	5.5	V
t _{CDR}	Chip Disable to Data Retention Time		0			ns
t _R	Recovery Time	t _{RC} = Read Cycle Timing	t _{RC}			ns



DPS256Q8-25, 35, 45, 55, 70, 85, 100 DC OPERATING CHARACTERISTICS: Over operating ranges

Symbol	Characteristics	Test Conditions	C		I		M/B		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	
I _{IN}	Input Leakage Current	V _{IN} = 0V to V _{CC}	-20	20	-20	20	-20	20	μA
I _{OUT}	Output Leakage Current	V _{I/O} = 0V to V _{CC} , CE or OE = V _{IH} , or WE = V _{IL}	-20	20	-20	20	-20	20	μA
I _{CC1}	Active Supply Current	CE = V _{IL} , V _{IN} = V _{IH} or V _{IL} , I _{OUT} = 0mA		310		360		365	mA
I _{CC2}	Operating Supply Current	Cycle = min., Duty = 100% I _{OUT} = 0mA		350		405		405	mA
I _{SB1}	Full Standby Supply Current (CMOS)	CE ≥ V _{CC} - 0.2V		16		16		16	mA
I _{SB2}	Standby Supply (TTL)	CE = V _{IH}		240		280		280	mA
I _{CCDR2}	Data Retention Supply Current	V _{DR} = 2V CE ≥ V _{DR} - 0.2V		2.8		3.2		6.4	mA
I _{CCDR3}	Data Retention Supply Current	V _{DR} = 3V CE ≥ V _{DR} - 0.2V		2.4		2.8		4.8	mA
V _{OL}	Output Low Voltage	I _{OUT} = 2.1mA		0.4		0.4		0.4	V
V _{OH}	Output High Voltage	I _{OUT} = -1.0mA	2.4		2.4		2.4		V

DPS256Q8-120, 150 DC OPERATING CHARACTERISTICS: Over operating ranges

Symbol	Characteristics	Test Conditions	C		I		M/B		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	
I _{IN}	Input Leakage Current	V _{IN} = 0V to V _{CC}	-20	20	-20	20	-20	20	μA
I _{OUT}	Output Leakage Current	V _{I/O} = 0V to V _{CC} , CE or OE = V _{IH} , or WE = V _{IL}	-20	20	-20	20	-20	20	μA
I _{CC1}	Active Supply Current	CE = V _{IL} , V _{IN} = V _{IH} or V _{IL} , I _{OUT} = 0mA		60		60		60	mA
I _{CC2}	Operating Supply Current	Cycle = min., Duty = 100% I _{OUT} = 0mA		75		80		85	mA
I _{SB1}	Full Standby Supply Current (CMOS)	CE ≥ V _{CC} - 0.2V		0.8		1.6		2.4	mA
I _{SB2}	Standby Supply (TTL)	CE = V _{IH}		16		16		16	mA
I _{CCDR2}	Data Retention Supply Current	V _{DR} = 2V CE ≥ V _{DR} - 0.2V		0.25		0.35		1.60	mA
I _{CCDR3}	Data Retention Supply Current	V _{DR} = 3V CE ≥ V _{DR} - 0.2V		0.35		0.40		1.95	mA
V _{OL}	Output Low Voltage	I _{OUT} = 2.1mA		0.4		0.4		0.4	V
V _{OH}	Output High Voltage	I _{OUT} = -1.0mA	2.4		2.4		2.4		V



DPS256Q8

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DPS256Q8-25, 35, 45, 55, 70, 85 AC Operating Conditions And Characteristics - READ CYCLE: Over operating ranges															
No.	Symbol	Parameter	-25		-35		-45		-55		-70		-85		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
1	t _{RC}	Read Cycle Time	25		35		45		55		70		85		ns
2	t _{AA}	Address Access Time		25		35		45		55		70		85	ns
3	t _{CO}	Chip Enable to Output Valid		25		35		45		55		70		85	ns
4	t _{OV}	Output Enable to Output Valid		15		20		25		35		40		60	ns
5	t _{OH}	Output Hold from Address Change	3		3		3		3		3		3		ns
6	t _{CLZ}	Chip Enable to Output in LOW-Z ^{4, 5}	5		5		5		5		5		5		ns
7	t _{OLZ}	Output Enable to Output in LOW-Z ^{4, 5}	5		5		5		5		5		5		ns
8	t _{CHZ}	Chip Enable to Output in HIGH-Z ^{4, 5}		15		15		20		25		30		30	ns
9	t _{OHZ}	Output Enable to Output in HIGH-Z ^{4, 5}		15		15		20		25		30		30	ns

DPS256Q8-25, 35, 45, 55, 70, 85 AC Operating Conditions And Characteristics - WRITE CYCLE ^{6,7} : Over operating ranges															
No.	Symbol	Parameter	-25		-35		-45		-55		-70		-85		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.			
10	t _{WC}	Write Cycle Time	25		35		45		55		70		85		ns
11	t _{AW}	Address Valid to End of Write	20		30		40		50		65		75		ns
12	t _{CW}	Chip Enable to End of Write	20		30		40		50		65		75		ns
13	t _{DW}	Data Valid to End of Write	15		20		25		25		30		35		ns
14	t _{DH}	Data Hold Time	3		3		3		3		3		0		ns
15	t _{WP}	Write Pulse Width	20		30		35		40		45		65		ns
16	t _{AS}	Address Set-up Time*	0		0		0		0		0		0		ns
17	t _{AH}	Address Hold Time	0		0		0		0		0		0		ns
18	t _{WHZ}	Write Enable to Output in HIGH-Z ^{4, 5}		15		15		15		20		25		30	ns
19	t _{WLZ}	Write Enable to Output in LOW-Z ^{4, 5}	5		5		5		5		5		5		ns

DPS256Q8-100, 120, 150 AC Operating Conditions And Characteristics - READ CYCLE: Over operating ranges													
No.	Symbol	Parameter	-100		-120		-150		Unit				
			Min.	Max.	Min.	Max.	Min.	Max.					
1	t _{RC}	Read Cycle Time	100		120		150		ns				
2	t _{AA}	Address Access Time			100		120		150	ns			
3	t _{CO}	Chip Enable to Output Valid			100		120		150	ns			
4	t _{OV}	Output Enable to Output Valid			60		60		70	ns			
5	t _{OH}	Output Hold from Address Change		10		10		10		ns			
6	t _{CLZ}	Chip Enable to Output in LOW-Z ^{4, 5}		10		10		10		ns			
7	t _{OLZ}	Output Enable to Output in LOW-Z ^{4, 5}		5		5		5		ns			
8	t _{CHZ}	Chip Enable to Output in HIGH-Z ^{4, 5}			35		40		50	ns			
9	t _{OHZ}	Output Enable to Output in HIGH-Z ^{4, 5}			35		40		50	ns			

DPS256Q8-100, 120, 150 AC Operating Conditions And Characteristics - WRITE CYCLE ^{6,7} : Over operating ranges													
No.	Symbol	Parameter	-100		-120		-150		Unit				
			Min.	Max.	Min.	Max.	Min.	Max.					
10	t _{WC}	Write Cycle Time	100		120		150		ns				
11	t _{AW}	Address Valid to End of Write	90		100		120		ns				
12	t _{CW}	Chip Enable to End of Write	90		100		120		ns				
13	t _{DW}	Data Valid to End of Write	40		50		60		ns				
14	t _{DH}	Data Hold Time	0		0		0		ns				
15	t _{WP}	Write Pulse Width	75		90		110		ns				
16	t _{AS}	Address Set-up Time*	0		0		0		ns				
17	t _{AH}	Address Hold Time	0		0		0		ns				
18	t _{WHZ}	Write Enable to Output in HIGH-Z ^{4, 5}			35		40		50	ns			
19	t _{WLZ}	Write Enable to Output in LOW-Z ^{4, 5}	5		5		5		5	ns			

* Valid for both Read and Write Cycles.

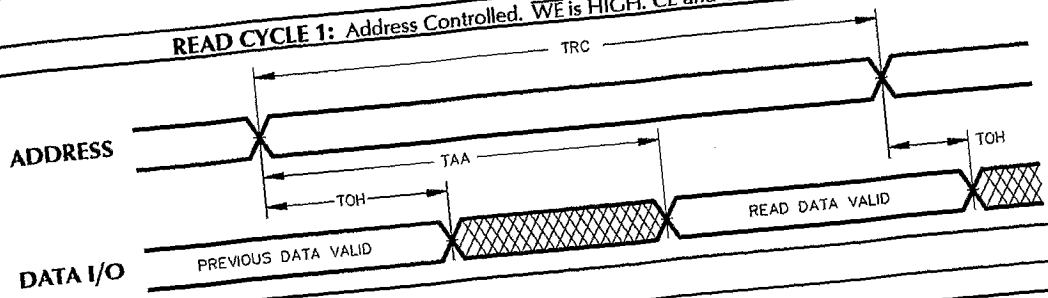


DPS256Q8

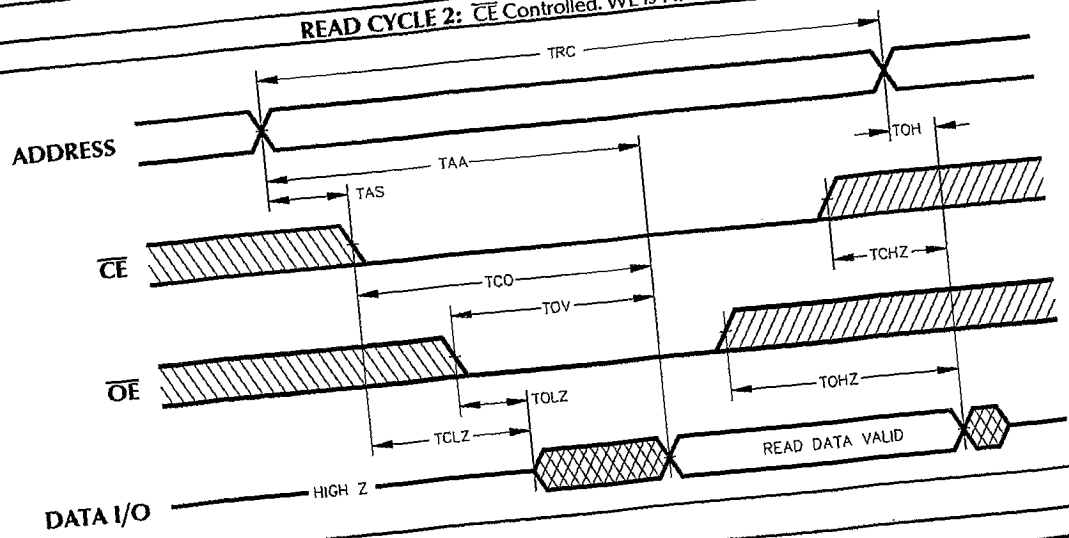
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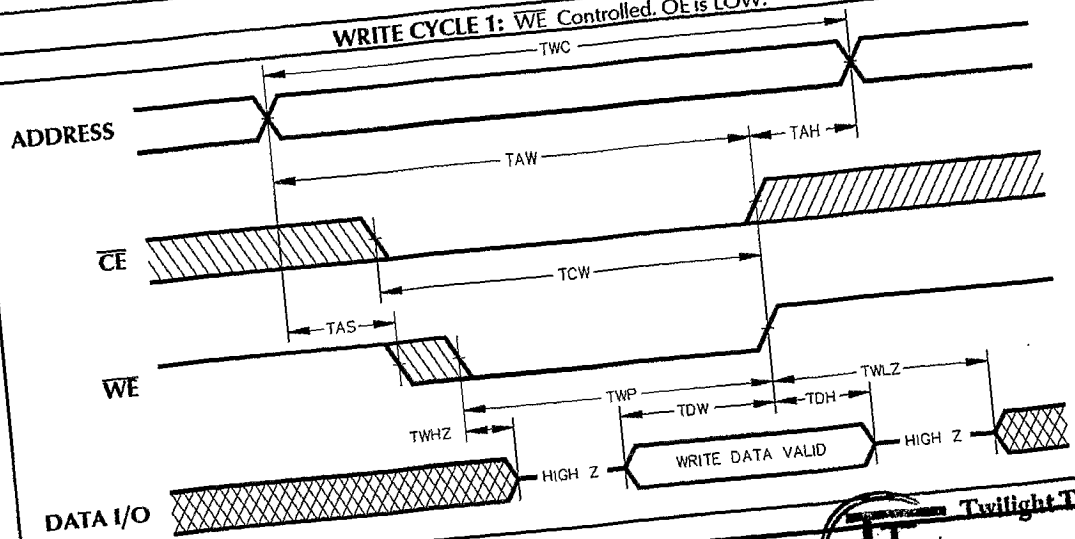
READ CYCLE 1: Address Controlled. WE is HIGH. CE and OE are LOW.

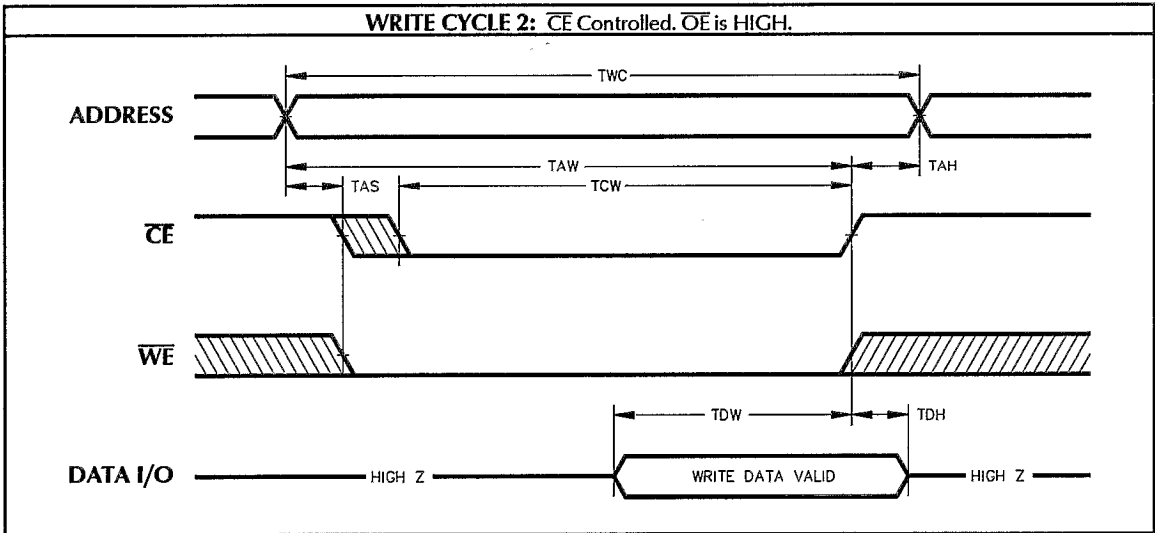


READ CYCLE 2: CE Controlled. WE is HIGH.



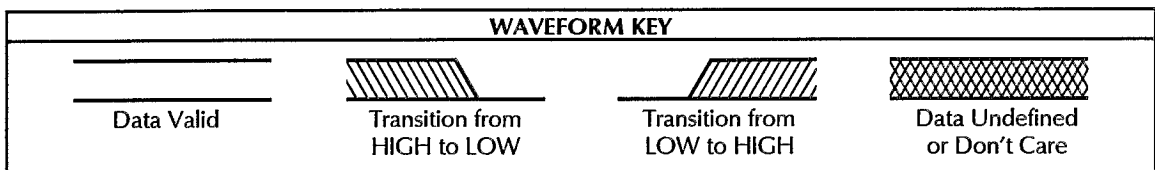
WRITE CYCLE 1: WE Controlled. OE is LOW.





NOTES:

1. All voltages are with respect to V_{SS} .
2. -2.0V min. for pulse width less than 20ns (V_{IL} min. = -0.5V at DC level).
3. Stresses greater than those under **ABSOLUTE MAXIMUM RATINGS** may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
4. This parameter is guaranteed and not 100% tested.
5. Transition is measured at the point of ± 500 mV from steady state voltage.
6. When \overline{OE} and \overline{CE} are LOW and \overline{WE} is HIGH, I/O pins are in the output state, and input signals of opposite phase to the outputs must not be applied.
7. The outputs are in a high impedance state when \overline{WE} is LOW.



ORDERING INFORMATION

DP S256Q8 - XXX X
PREFIX DEVICE TYPE SPEED GRADE

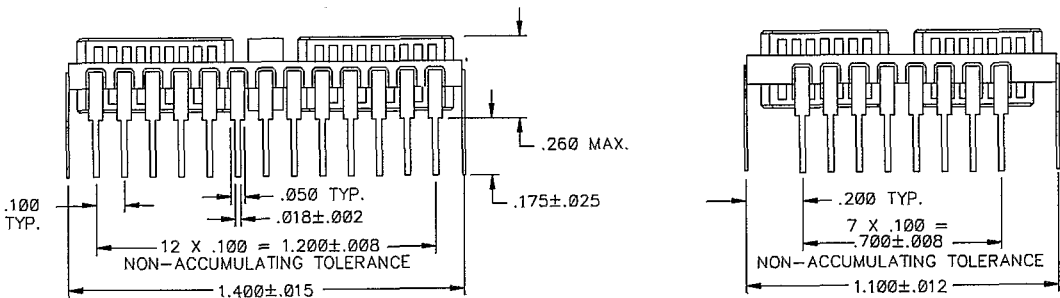
C	COMMERCIAL	0°C to +70°C
I	INDUSTRIAL	-40°C to +85°C
M	MILITARY	-55°C to +125°C
B*	MIL-PROCESSED	-55°C to +125°C

25	25ns
35	35ns
45	45ns
55	55ns
70	70ns
85	85ns
100	100ns
120	120ns
150	150ns

CMOS SRAM 256K X 8 CER-QUAD PACKAGE

* B grade modules can be constructed with 883 devices.

MECHANICAL DIAGRAMS



Dense-Pac Microsystems, Inc.

7321 Lincoln Way • Garden Grove, California 92641-1428
 (714) 898-0007 • (800) 642-4477 (Outside CA) • FAX: (714) 897-1772

